



US00D487885S

(12) **United States Design Patent**  
**Fan**

(10) **Patent No.:** **US D487,885 S**

(45) **Date of Patent:** **\*\* Mar. 30, 2004**

(54) **HEAT PIPE HEAT SINK ASSEMBLY**

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(73) **Assignee:** **Datech Technology Co., Ltd., Taipei Hsien (TW)**

(\*\*) **Term:** **14 Years**

(21) **Appl. No.:** **29/180,906**

(22) **Filed:** **May 2, 2003**

(30) **Foreign Application Priority Data**

Mar. 14, 2003 (TW) ..... 092301452

(51) **LOC (7) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/179**

(58) **Field of Search** ..... D13/179; 174/15.1, 174/16.3; 165/80.3, 80.4, 121, 122, 125, 131, 140, 146, 148, 185; 257/670, 675, 676, 706, 707, 712, 718, 719, 720, 721, 722; 361/695, 697, 699, 702, 704, 709, 514

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(57) **CLAIM**

The ornamental design for a heat pipe heat sink assembly, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a heat pipe heat sink assembly, in accordance with the present invention;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

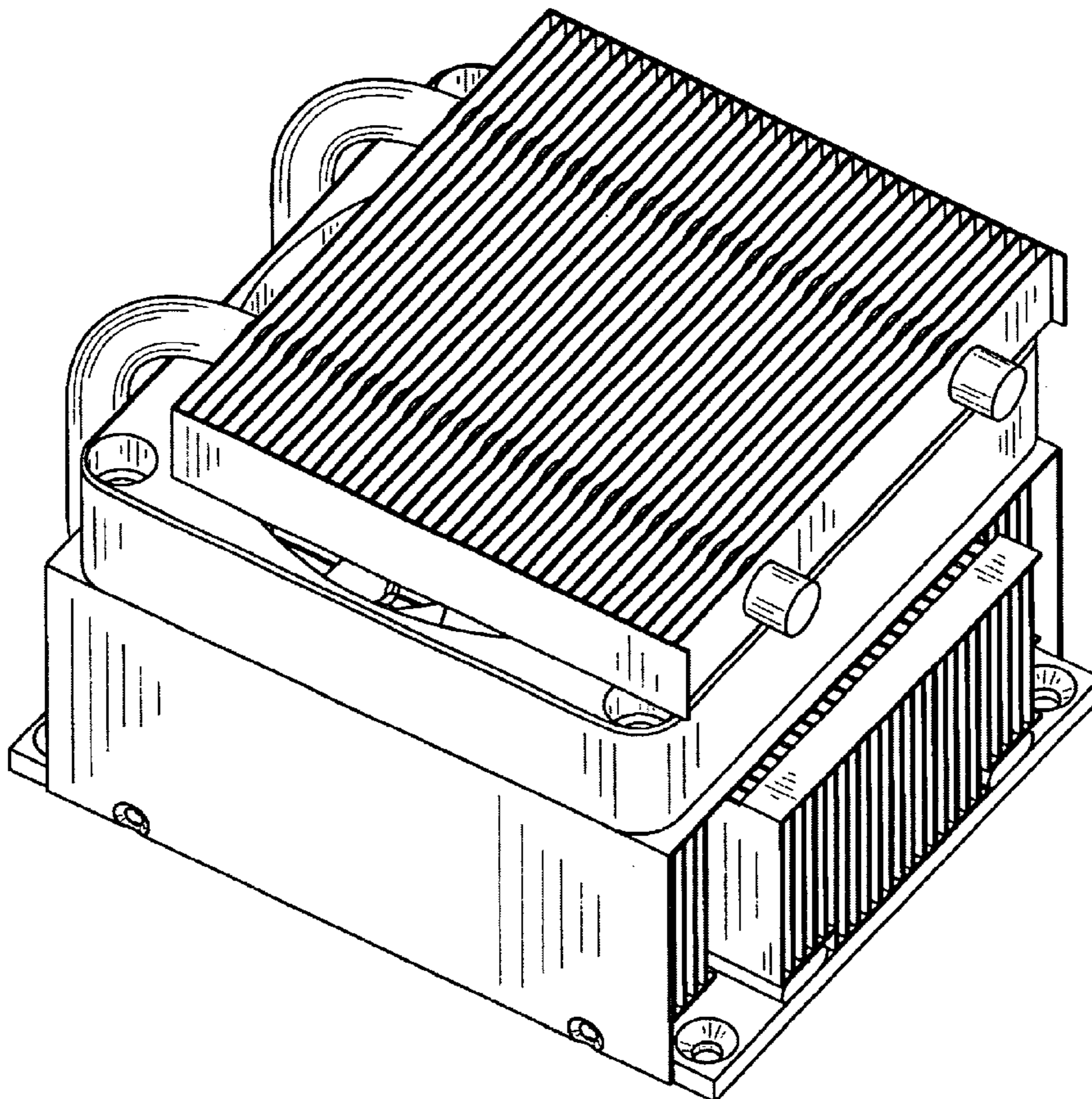
FIG. 4 is a left side elevational view thereof;

FIG. 5 is a right side elevational view thereof;

FIG. 6 is a top plan view thereof; and,

FIG. 7 is a bottom plan view thereof.

**1 Claim, 7 Drawing Sheets**



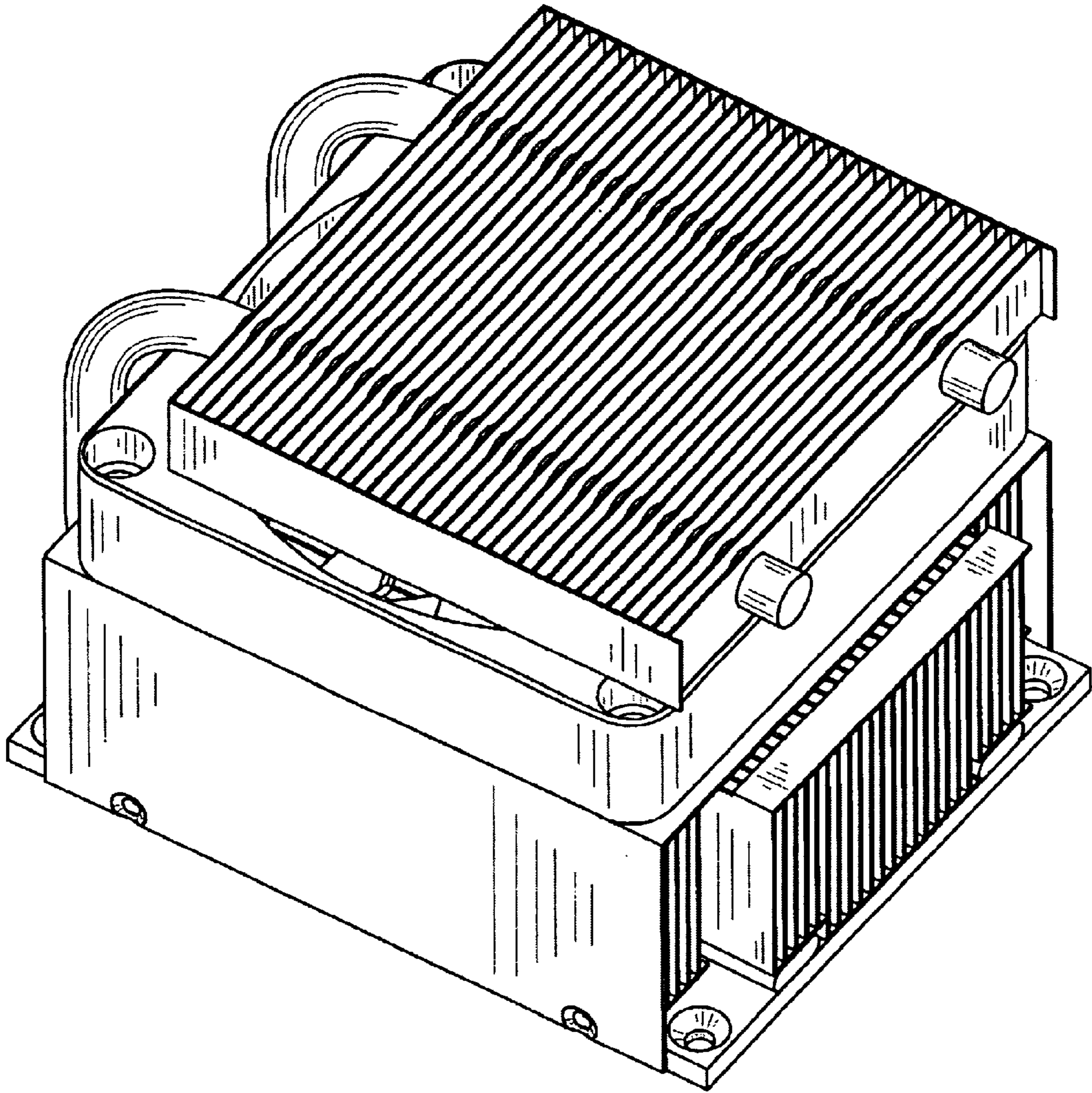


FIG. 1

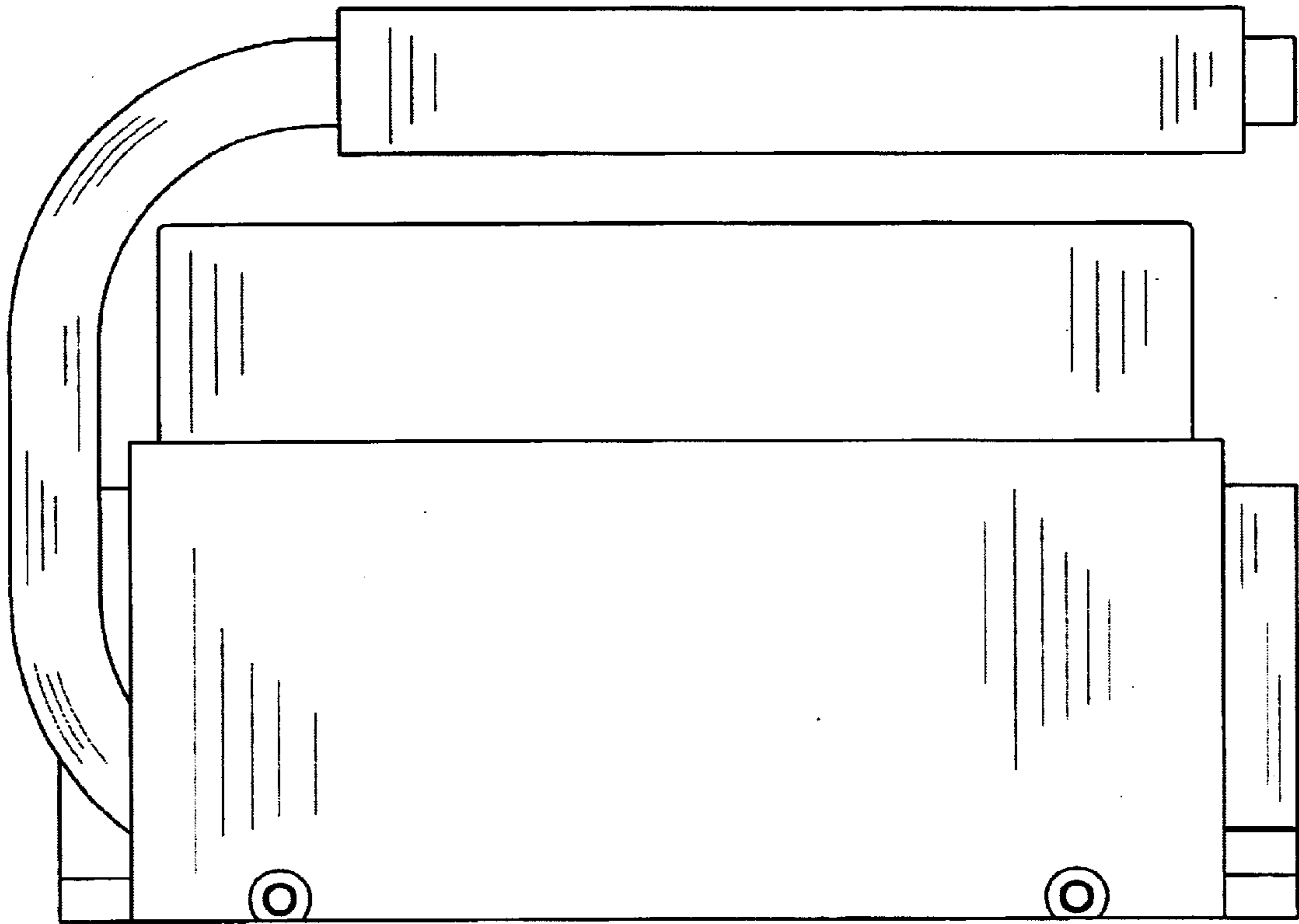


FIG. 2

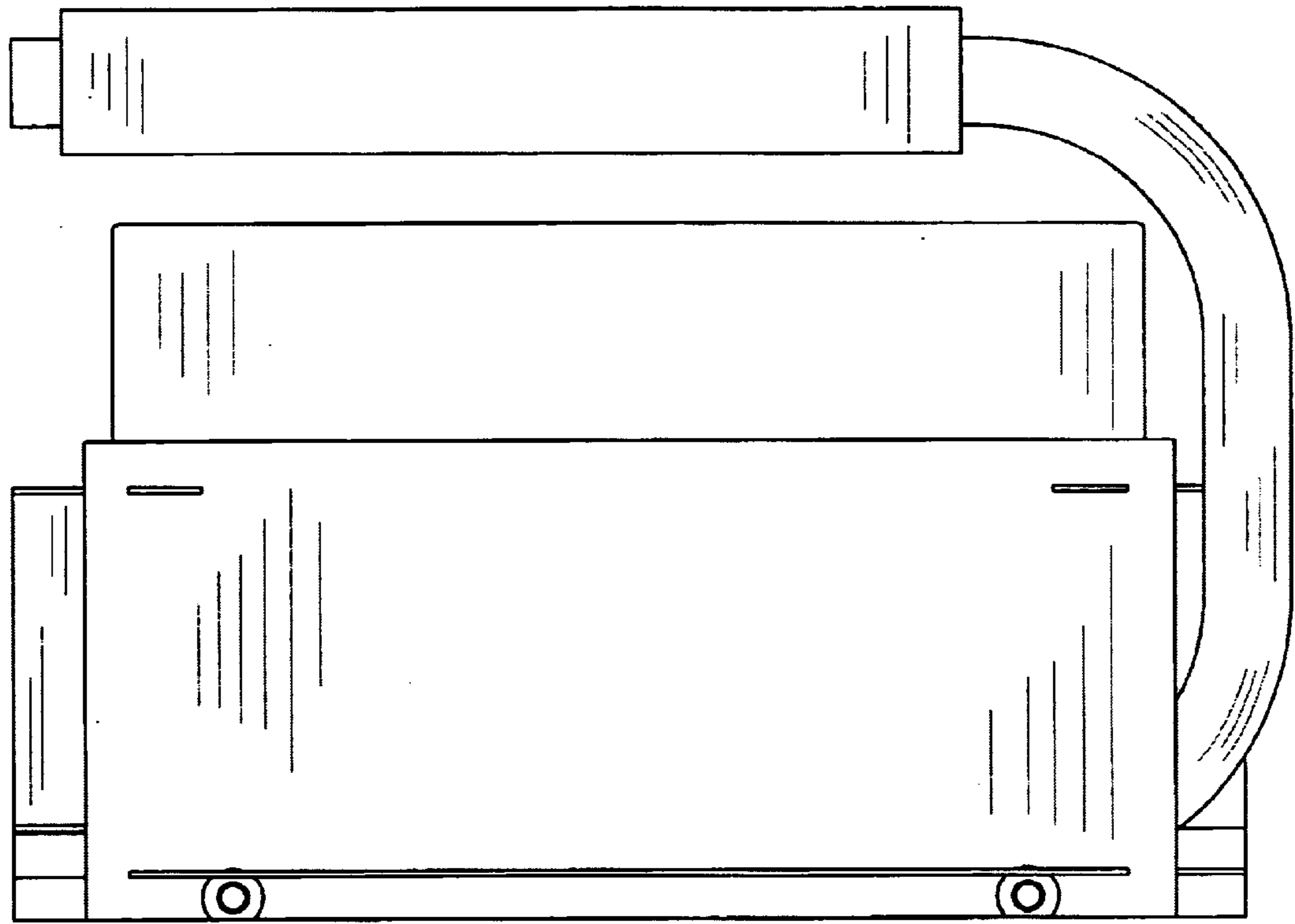


FIG. 3



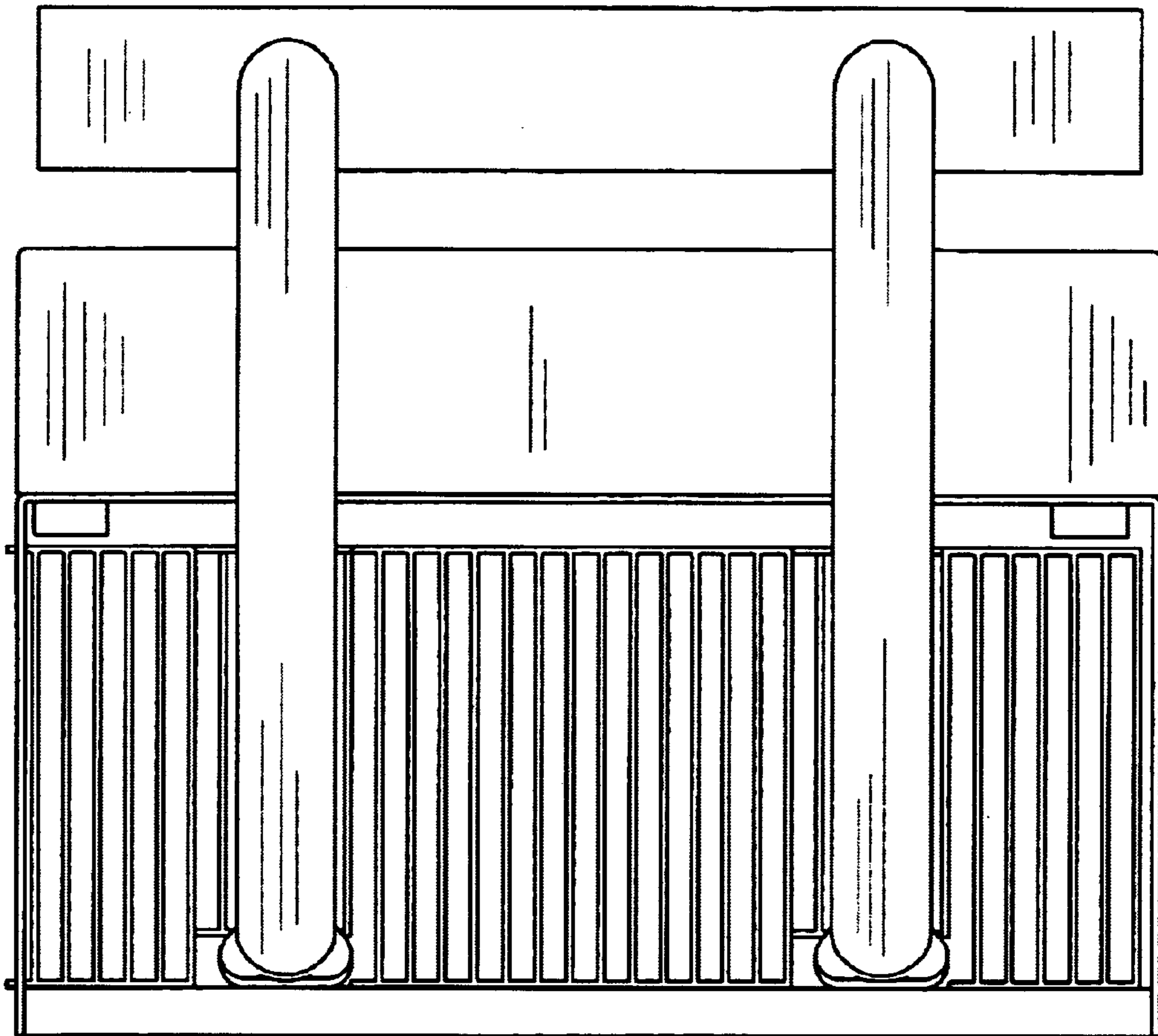


FIG. 4

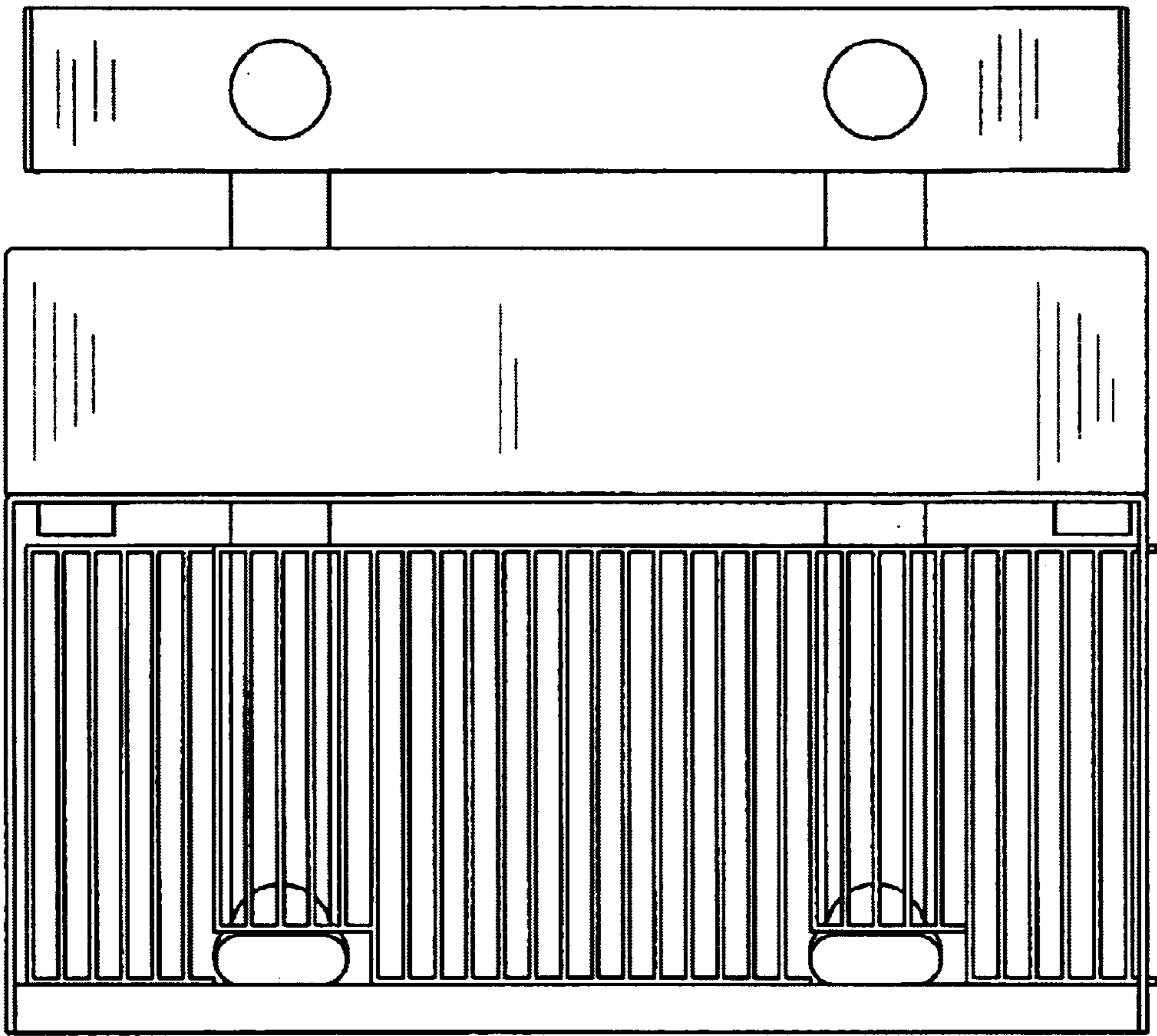


FIG. 5

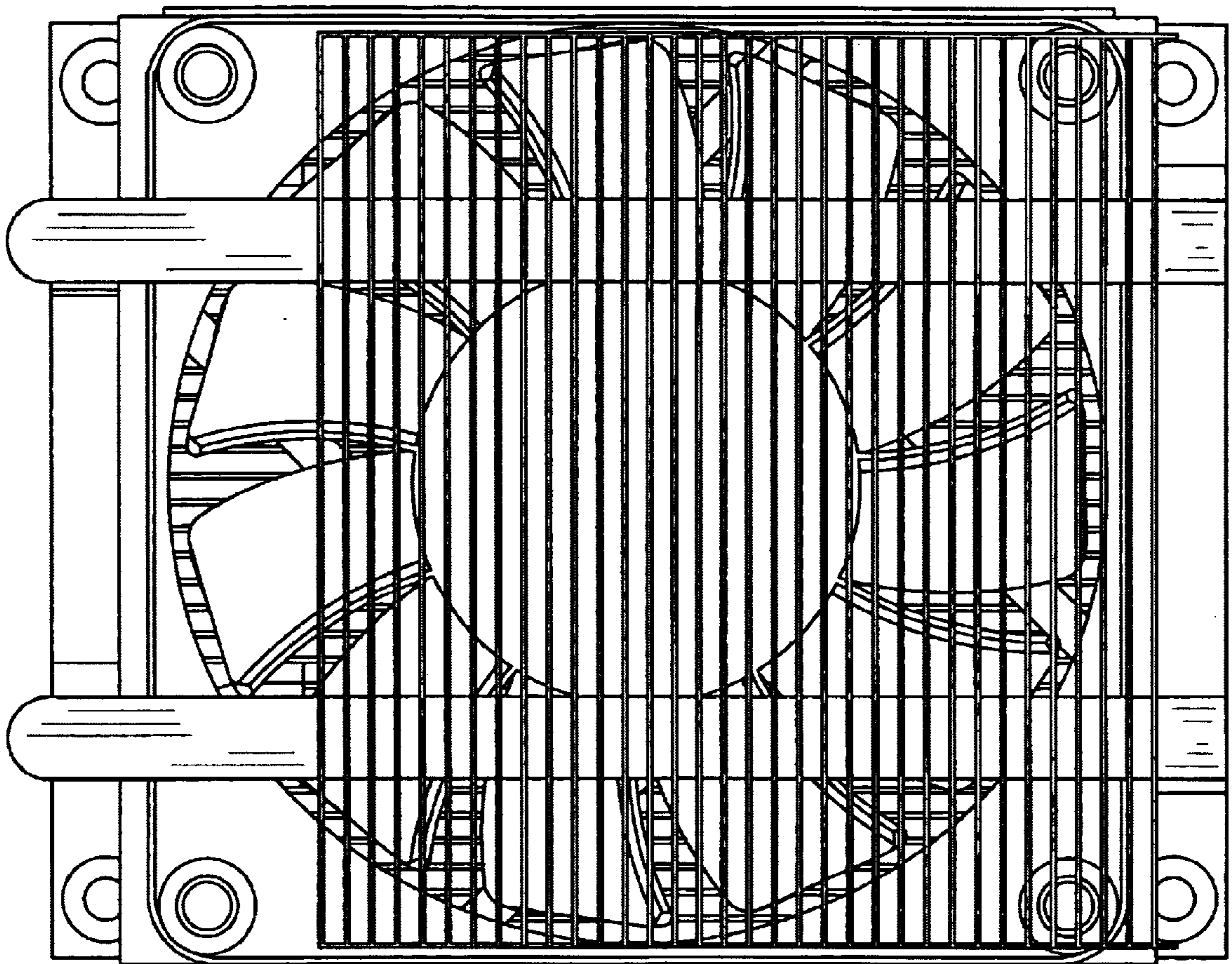


FIG. 6

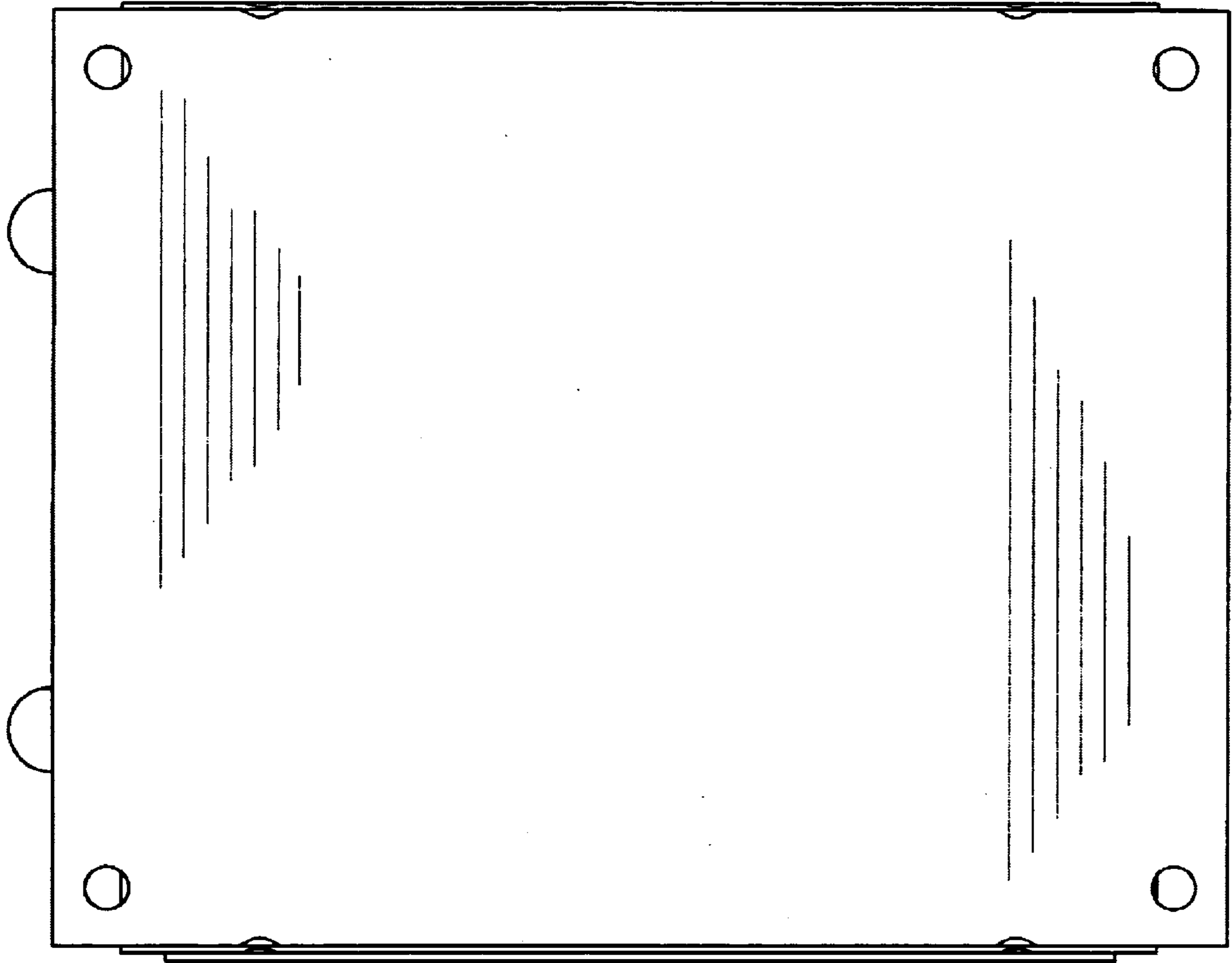


FIG. 7